

/ Revised record

A	2019-7-23	ALL	SMC-A-S8KC_S8MC-8A1KV		
B	2021-2-9	2/8			

800~1000V

8.0A SMC

Surface Mount General Purpose Silicon Rectifier, Reverse Voltage: 800 to 1000 V, Forward Current:8.0A ,SMC package.

RoHS 2011/65/EU

Glass Passivated Chip Junction,Lead free in comply

参数 Parameter	符号 Symbol	数值 Rating		单位 Unit
		S8KC	S8MC	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	1000	V
Maximum RMS voltage	V_{RMS}	560	700	V
Maximum DC Blocking Voltage	V_{DC}	800	1000	V
Maximum Average Forward Rectified Current	$I_F (AV)$	8.0		A

/ Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve



Fig.2 Typical Reverse Characteristics



Fig.3 Typical Forward Characteristic

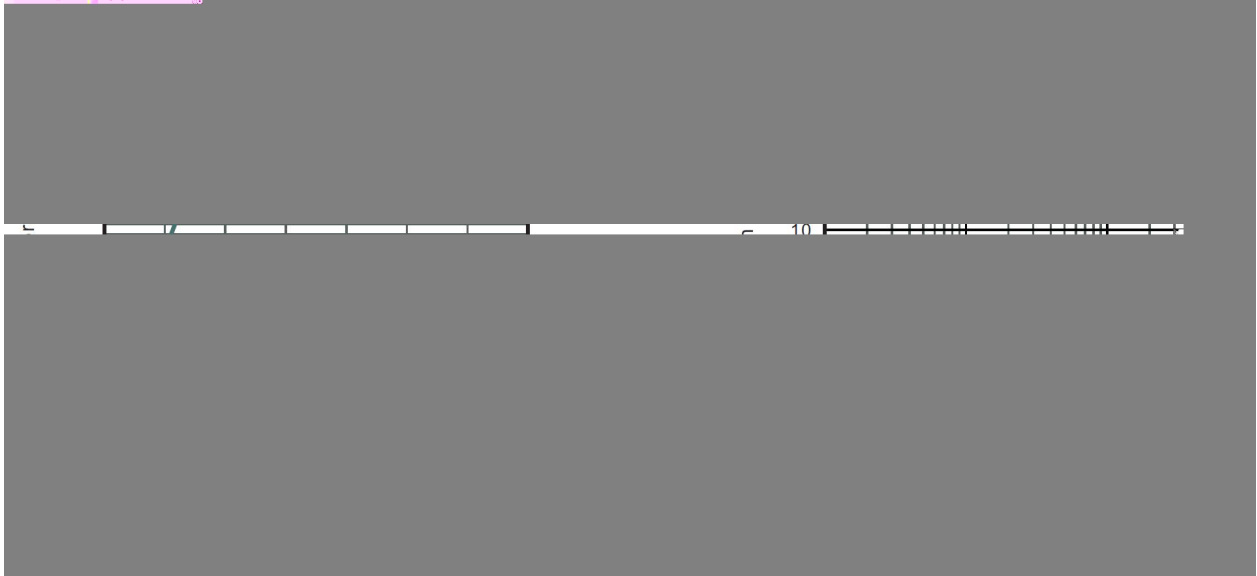
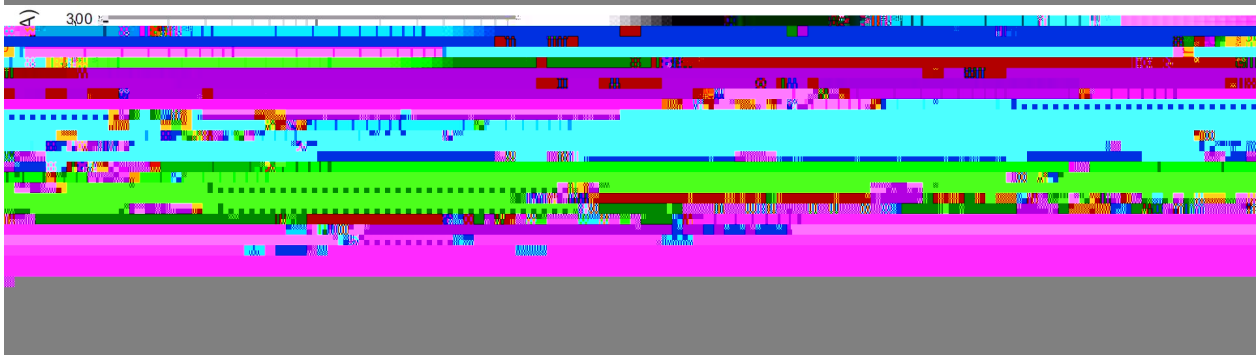
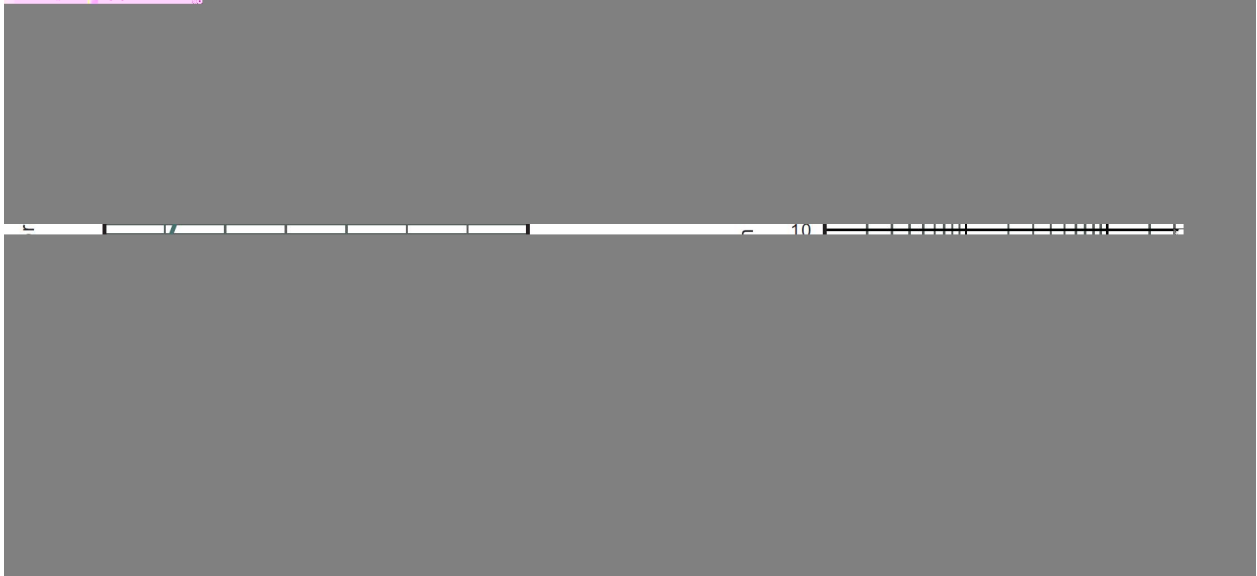
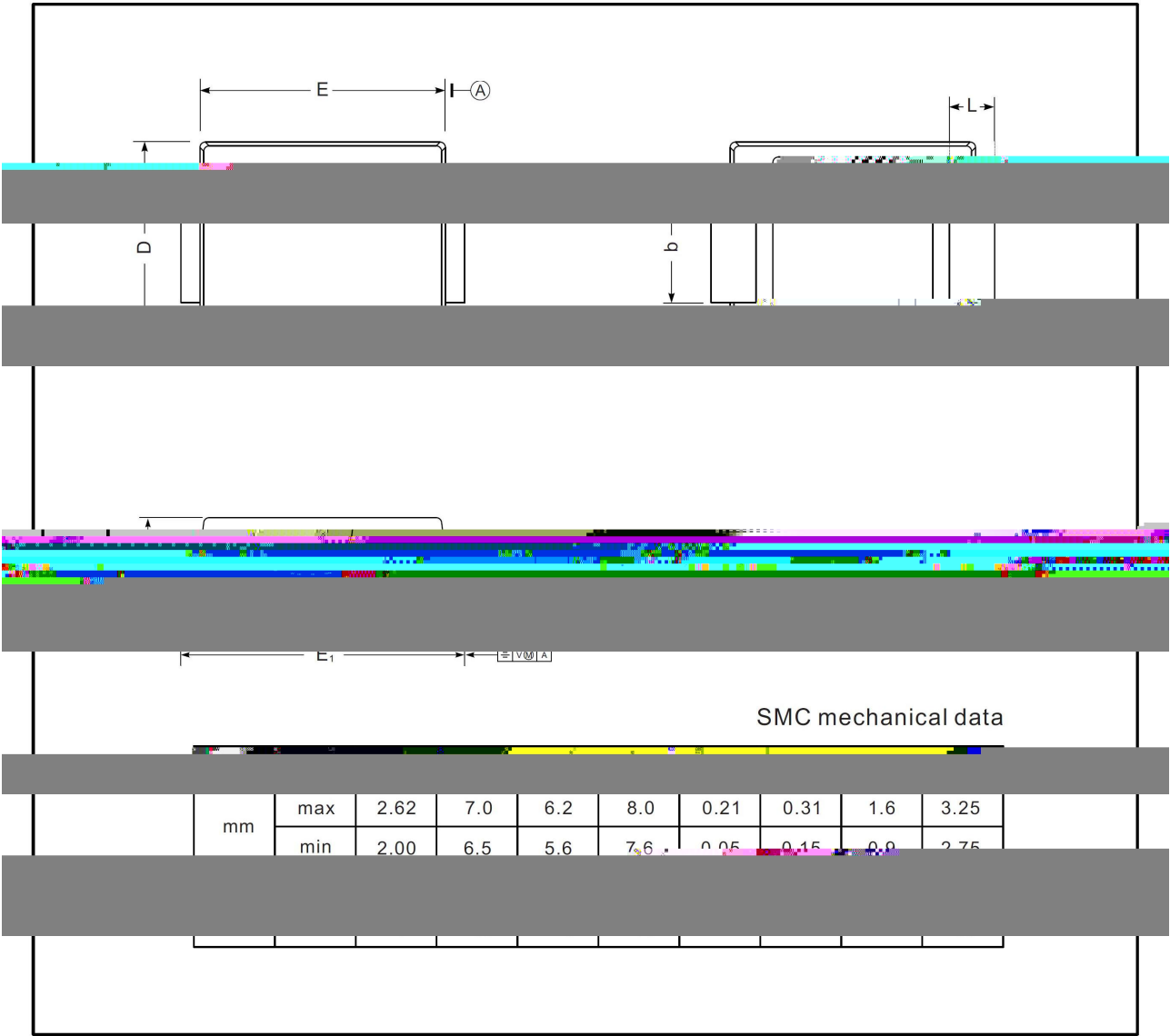


Fig.4 Typical Junction Capacitance



/ Package Dimensions

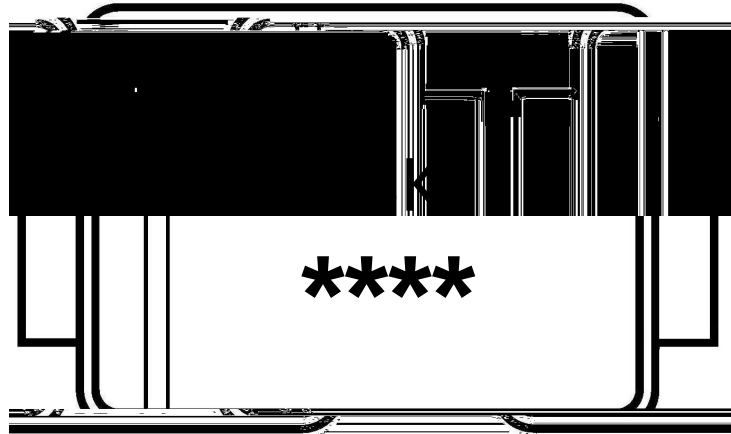
SMC



Marking

Type number	Marking code
S8KC	S8K

/ Marking Instructions



S8K

1 *

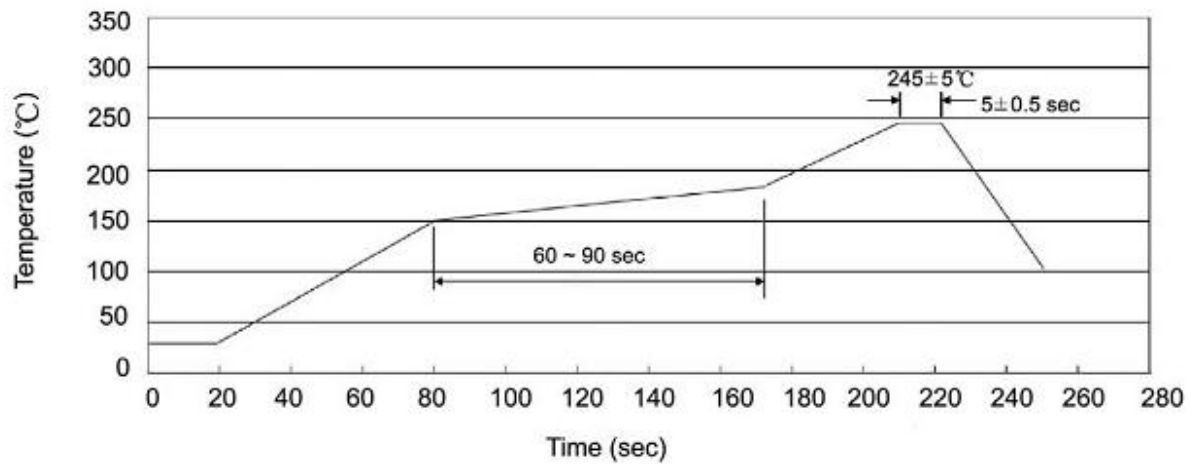
3 *

Note:

S8K Product Type Code

***** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No
Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱			
SMC	3000	2	6000	6	36000	13" ×16	337X337X49	380X335X366

/ Notices